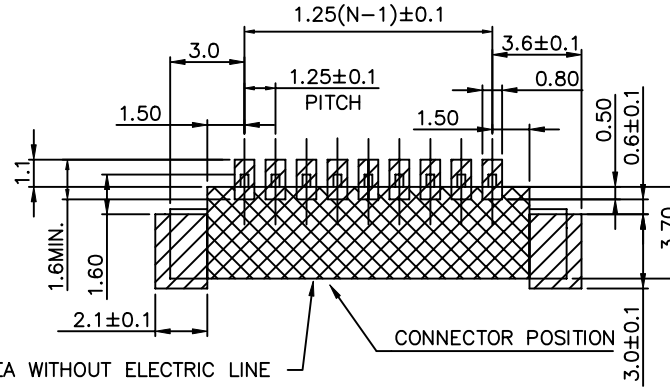
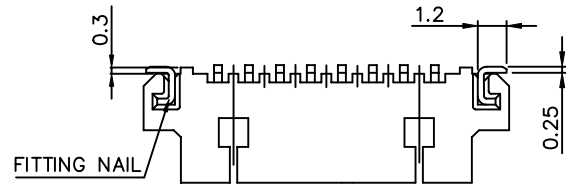
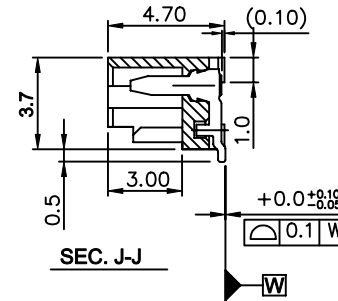
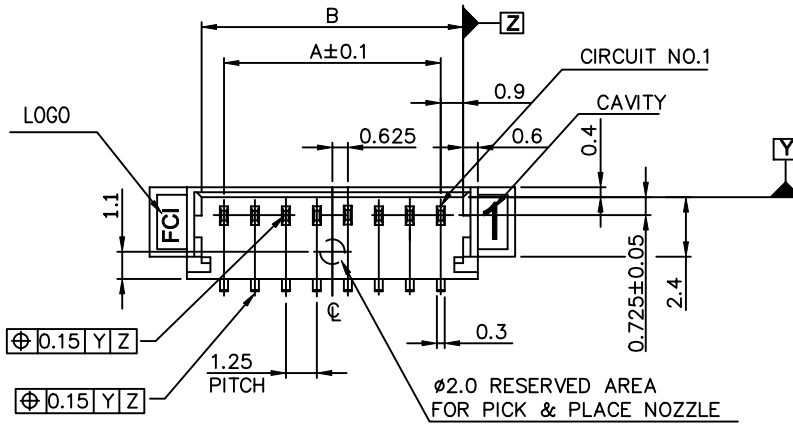




RECOMMENDED P.C.BOARD PATTERN DIM.(REF)



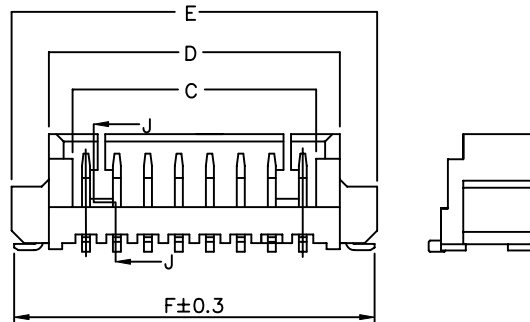
- NOTES:
1. MATERIAL:
 - 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0.
 - 1.2 CONTACT: COPPER ALLOY
 - 1.3 FITTING NAIL: COPPER ALLOY
 2. FINISH:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - CONTACT AREA AND SOLDER TAIL: MATTE TIN 100u" MIN. OVERALL
 - FITTING NAIL:
 - UNDER PLATING: 50u" MIN. NICKEL OVERALL
 - MATTE TIN PLATING 100u" MIN. OVERALL
 3. REFLOW SOLDER CAPABLE TO 260°C PEAK TEMP. FOR 10 SECONDS MAX.
 4. SPEC. PLS. REFER TO GS-12-571.
 5. PACKAGE PLS. REFER TO GS-14-1313.
 6. APPLY EVEN CIRCUIT PRODUCTS.
 7. PART NUMBER DESCRIPTION:

10089714-XXX X X X LF

NO OF CONTACTS
PACKING
0: TAPE & REEL

LEAD FREE
COLOR
0: NATURAL(WHITE)
PLATING
0: MATTE TIN

CKT	Dim.A	Dim.B	Dim.C	Dim.D	Dim.E	Dim.F
003	2.50	4.30	3.60	5.50	8.50	8.40
004	3.75	5.55	4.85	6.75	9.75	9.65
005	5.00	6.80	6.10	8.00	11.00	10.90



mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI			
ltr	ecn no	dr	date	linear	.X ± 0.25	projection	title	www.fciconnect.com			
A	T08-1164	WL	08/11/08		.XX ± 0.15		1.25mm S/T WIRE TO BOARD SMT TYPE				
B	T08-1185	WL	11/13/08		.XXX ± 0.10						
C	T08-1196	WL	12/10/08	angles	0° ± 2°						
D	T09-1005	WL	01/20/09	dr	LEIF SHEN 06/18/08	MM					
E	T09-1146	WL	11/16/09	enrg	LEIF SHEN 06/18/08						
F	T10-0009	WL	01/20/10	chr	LEIF SHEN 06/18/08	scale					
G	T10-0183	WL	11/30/10	appd	JOSEPH HSIA 06/18/08						
sheet index	revision	G	1								